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Part Number: [0780790051](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Vertical, Through Hole, with Beveled Metal Pins, Black Housing, Off-White Latches, 0.38µm (15µ") Gold(Au) Plating, 2.67mm(.105") Solderail, 240 Circuits, Lead free

Documents:

[3D Model](#) [Product Specification PS-78079-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [78079](#)
 Component Type Socket
 JEDEC Outline MO-269
 Product Name DDR3 DIMM

Physical

Circuits (Loaded) 240
 Circuits (maximum) 240
 Color - Resin Black, Natural
 Durability (mating cycles max) 25
 Entry Angle Vertical
 Flammability 94V-0
 Function Key None
 Keying to Mating Part Yes
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.105 In
 PC Tail Length (mm) 2.67 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.57 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Pitch - Term. Interface (in) 0.039 In
 Pitch - Term. Interface (mm) 1.00 mm
 Plating min: Mating (µin) 15
 Plating min: Mating (µm) 0.38
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
 Voltage - Maximum 30V AC (RMS)/DC
 Voltage Key Center

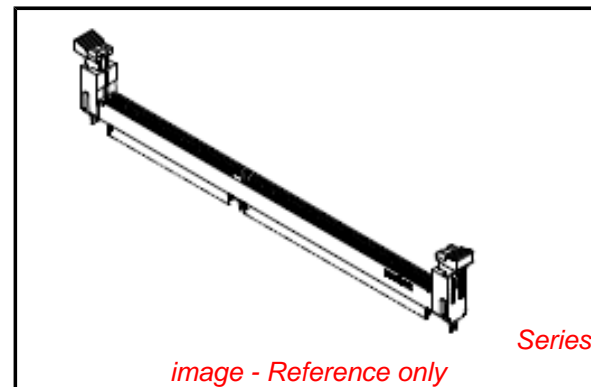


image - Reference only

EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Halogen-Free
 Status**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[78079Series](#)

Mates With

JEDEC standard 1.27mm modules

Solder Process Data

Duration at Max. Process Temperature (seconds)	10
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	240

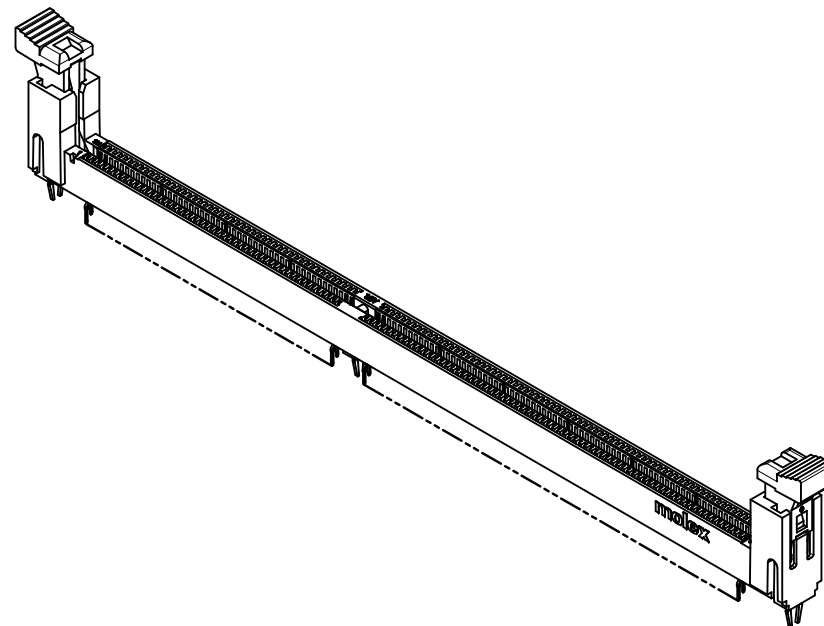
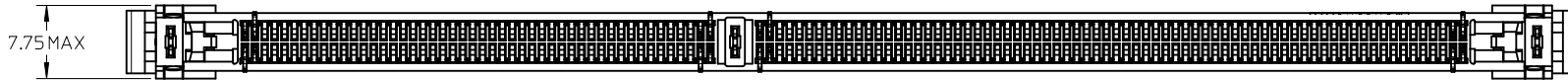
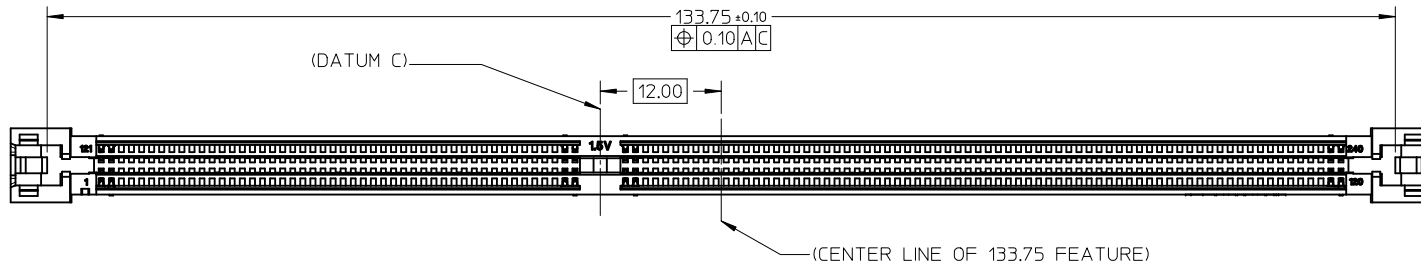
Material Info**Reference - Drawing Numbers**

Product Specification	PS-78079-001
Sales Drawing	SD-78079-001

This document was generated on 04/19/2010

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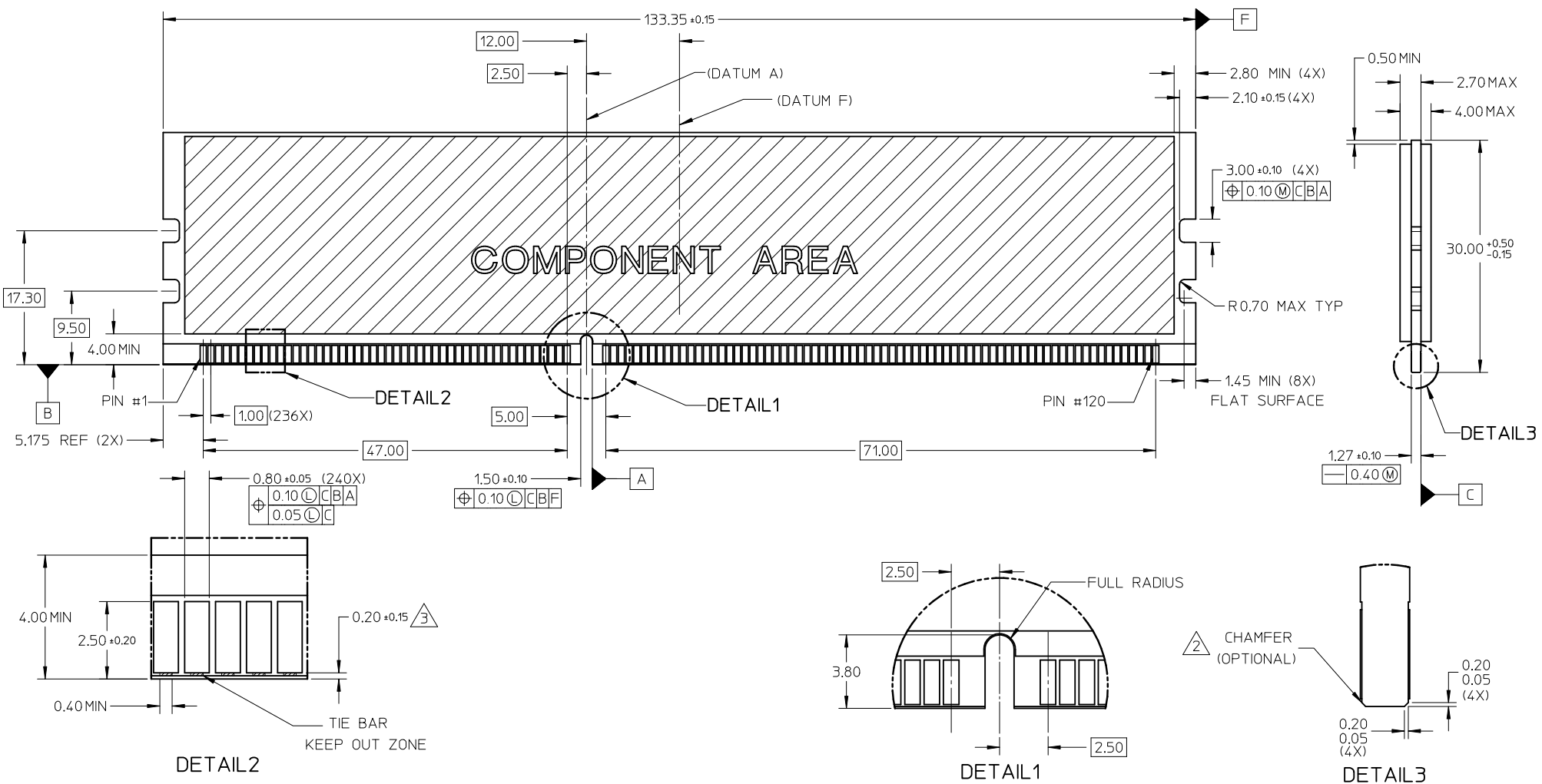
10 9 8 7 6 5 4 3 2 1



FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE			
			ANGULAR ± 1 °	CHECKED BY SHLENI	DATE 2006/09/07	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY SHLENI	DATE 2010/06/10	MOLEX INCORPORATED			
A4				MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78079-001	SHEET NO. 2 OF 8			

9 8 7 6 5 4 3 2 1

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, MAY 06)

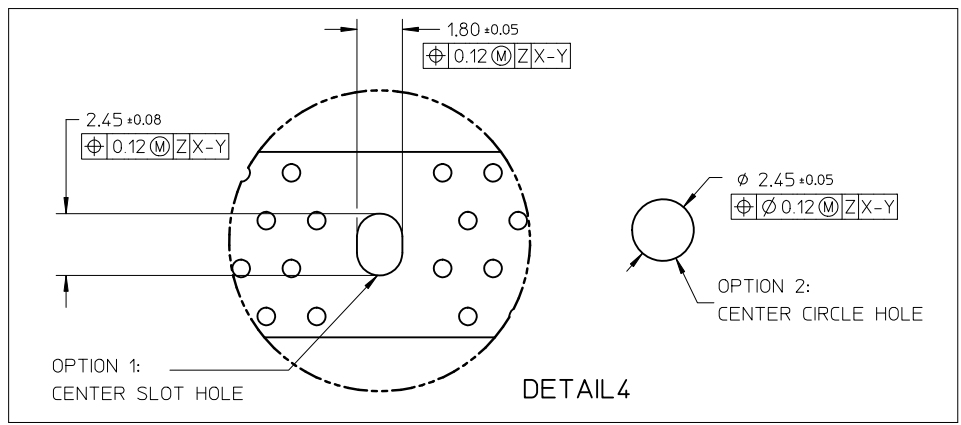
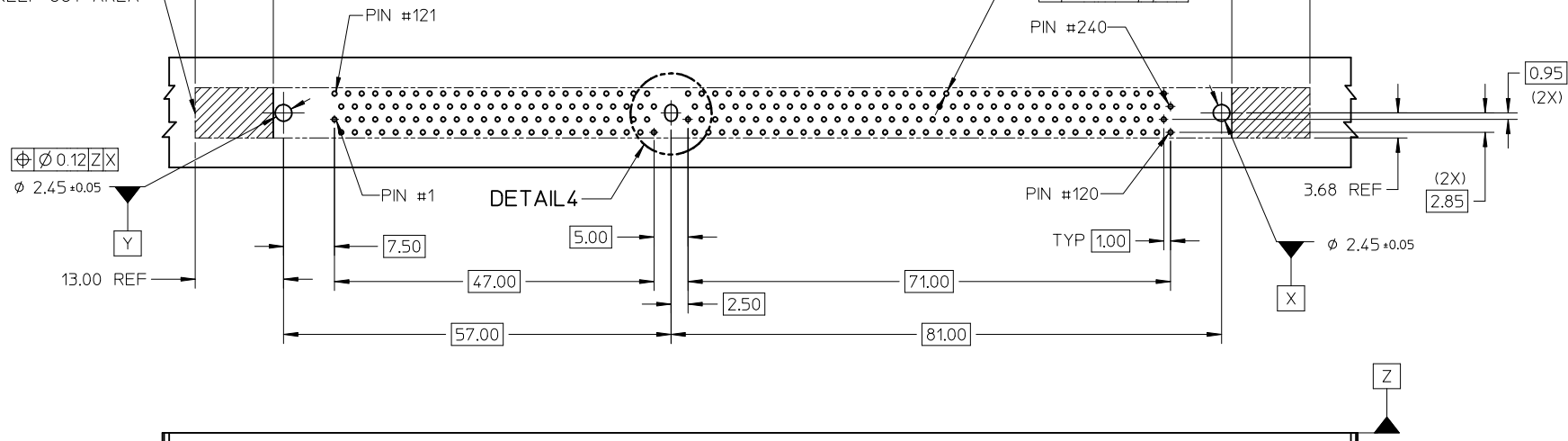


- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHYK: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H
		mm	INCH																	
	4 PLACES	± ---	± ---																	
	3 PLACES	± ---	± ---																	
2 PLACES	± 0.2	± ---																		
1 PLACE	± ---	± ---																		
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-78079-001	SHEET NO.: 3 OF 8	MOLEX INCORPORATED																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE: A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																			
REV: A4																				

10 9 8 7 6 5 4 3 2 1

KEEP OUT AREA

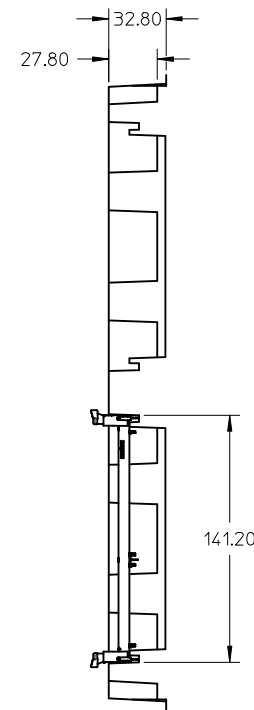
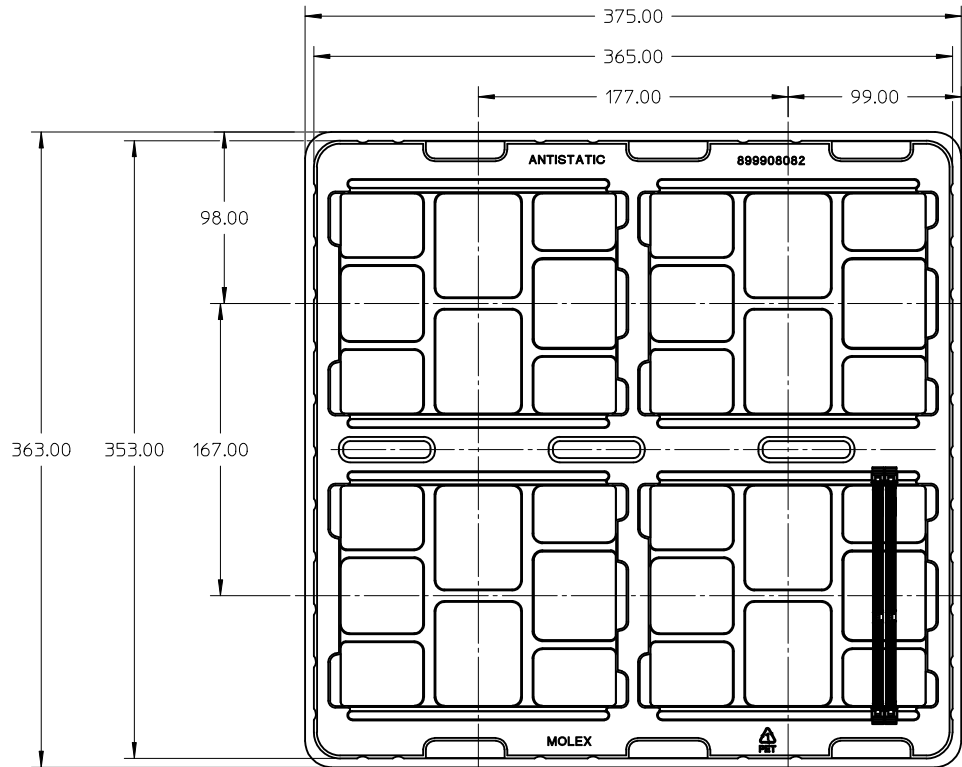


NOTE:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES \pm --- \pm --- 3 PLACES \pm --- \pm --- 2 PLACES ± 0.2 \pm --- 1 PLACE \pm --- \pm ---	mm INCH \pm --- \pm --- \pm --- \pm --- ± 0.2 \pm --- \pm --- \pm ---	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
		ANGULAR $\pm 1^\circ$	APPROVED BY SHLENI	DATE 2010/06/10	MOLEX INCORPORATED				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO. SD-78079-001	DOCUMENT NO.	SHEET NO. 4 OF 8				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



NOTES:
1. QTY OF CAVITY: 20 X 4 = 80 PCS

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	4 PLACES	± ---	± ---	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H		
	$F_C=0$	3 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/09/07	MATERIAL NO. SEE TABLE		
	$F_P=0$	2 PLACES	± 0.2	± ---	APPROVED BY SHLENI	DATE 2010/06/10	DOCUMENT NO. SD-78079-001		
		1 PLACE	± ---	± ---	ANGULAR ± 1 °		SHEET NO. 5 OF 8		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION		
78079-0001	CENTRE (1.5V)	BLACK	BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001		
78079-0003				3.00	2.18				
78079-0002				3.18	2.36				
78079-0011				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002	
78079-0013				3.00	2.18				
78079-0012				3.18	2.36				
78079-0021				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-003	
78079-0023				3.00	2.18				
78079-0022				3.18	2.36				
78079-0051			NATURAL (OFFWHITE)		0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0053							2.67	1.57	
78079-0052							3.00	2.18	
78079-0061					3.18		2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0063					2.67		1.57		
78079-0062					3.00		2.18		
78079-0071					3.18		2.36	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0073					2.67		1.57		
78079-0072					3.00		2.18		

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	mm INCH DRAWN BY DATE YTYANG01 2006/08/11 CHECKED BY DATE SHLENI 2006/09/07 APPROVED BY DATE SHLENI 2010/06/10	TITLE	DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MOLEX INCORPORATED			
	A4			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
						6 OF 8	

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION	
78079-0201	CENTRE (1.5V)	BLUE	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001	
78079-0203				3.00	2.18			
78079-0202				3.18	2.36			
78079-0211				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002
78079-0213				3.00	2.18			
78079-0212				3.18	2.36			
78079-0221		2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003			
78079-0223		3.00	2.18					
78079-0222		3.18	2.36					
78079-0351		GREEN	NATURAL (OFFWHITE)	2.67		1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0353				3.00		2.18		
78079-0352				3.18		2.36		
78079-0361				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002	
78079-0363				3.00	2.18			
78079-0362				3.18	2.36			
78079-0371				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-003
78079-0373				3.00	2.18			
78079-0372		3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H			
	A4	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-78079-001		SHEET NO. 7 OF 8	
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

E

D

C

B

A

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION			
78079-0101	CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0103				3.00	2.18					
78079-0102				3.18	2.36					
78079-0111							2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0113							3.00	2.18		
78079-0112							3.18	2.36		
78079-0121							2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0123							3.00	2.18		
78079-0122				3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DRAWN BY DATE YTYANG01 2006/08/11 CHECKED BY DATE SHLENI 2006/09/07 APPROVED BY DATE SHLENI 2010/06/10	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. MOLEX INCORPORATED SD-78079-001	SHEET NO. 8 OF 8		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				